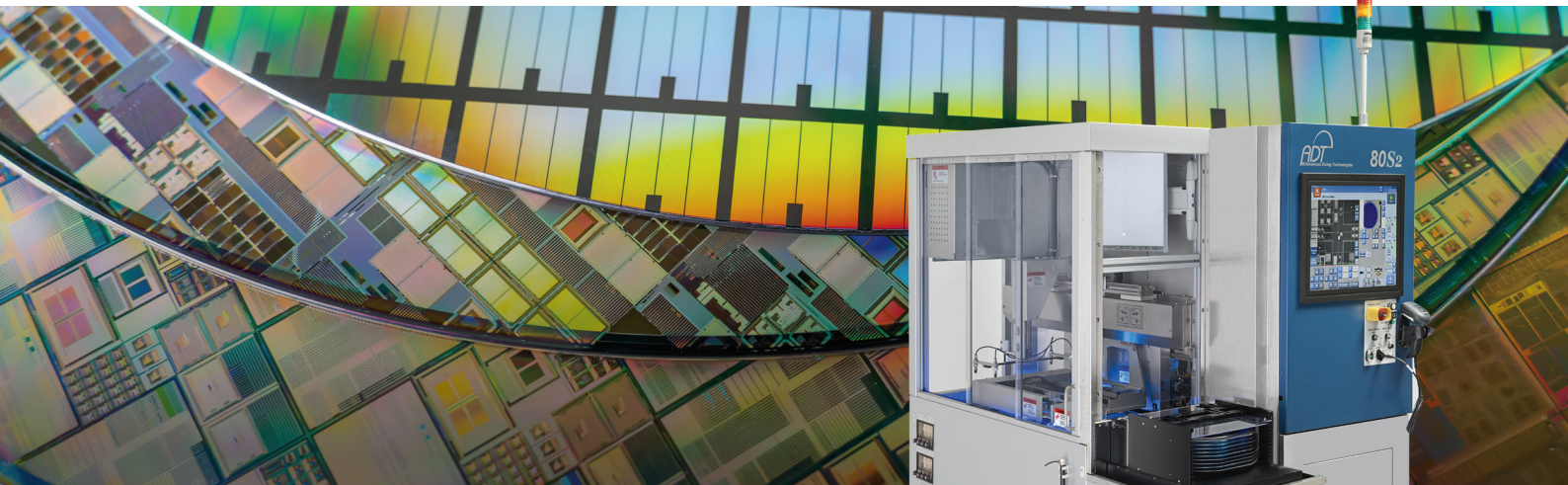
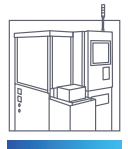




ADT Dicing Saw Platform

Reliable. High-performance. Low Cost of Ownership.

Advanced Dicing Technologies (ADT) is a global leader in precision dicing solutions for the semiconductor industry. With decades of experience in wafer singulation, ADT provides reliable, high-performance dicing systems that deliver exceptional cutting accuracy, productivity, and low cost of ownership.

The ADT 80S2 is the latest generation fully automatic twin-spindle dicing saw, designed to meet the demanding requirements of high-volume semiconductor manufacturing. Built on ADT's proven technology platform, the 80S2 combines superior cutting performance, advanced automation, and full compliance with the SEMI-S2 Safety Guideline, making it an ideal solution for modern production environments.

SEMI-S2 Compliance

The ADT 80S2 has been designed in accordance with the SEMI-S2 Environmental, Health and Safety Guideline for Semiconductor Manufacturing Equipment.

Configuration

- Blade O.D.: 2"
- Frame Size: Ø6", Ø8", Ø12"



Features and Benefits

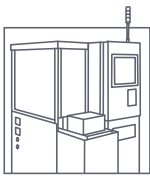
- Dual microscopes, fixed non-contact sensors
- Spindles of 1.9 kW
- Superior vision system with continuous zoom magnification
- Built-in CO2 Bubbler
- Integrated ESD kit

Ease of Use

- The 80S2 operates with the ADT intuitive New Graphic
- User Interface (NGUI) and includes two touch-screens: a 19" monitor for the main screen and a 17" monitor for the maintenance screen

Other Key Features of Importance

- High dicing process speeds
- Industrial PC based on Win 11 OS
- Air bearing feed axis (X-axis)
- Fast & Simple blade change
- Fast automatic alignment and cut positioning for increased throughput
- Automatic Kerf inspection and quality analysis for maximum precision
- Process data logging and statistical analysis
- SECS / GEM platform ready



80S2 Fully Automatic Twin Dicing Saw

Specifications

Specification	Value
Workpiece Size	Ø 6", 8", Ø 12"
Spindle	Two facing spindles 1.9kW, max. 60,000 rpm
Blade Size	2"
Y1 / Y2-Axis Drive Control Resolution Cumulative Accuracy Indexing Accuracy Cutting range	Ball bearing lead screw Linear encoder for each Y-Axis 0.1 µm 1.5 µm 1.0 µm 350 mm
X-Axis Drive Feed rate Cutting range	Air Slide Ball bearing lead screw Up to 1000 mm/sec 420 mm
Z1 / Z2 Axis Drive Resolution Repeatability Max/ stroke	Ball bearing lead screw 0.2 nm 1.0 µm 50 mm (for 2.188" blade OD)
θ Axis Drive Repeatability Stroke	Closed-loop, Direct-drive 4 arc-sec 380°
Vision System	USB 3 camera, High bright LED illumination (vertical & oblique)
Cleaning Station Spining Speed Cleaning Method	Full rines and dry cycle 100-3,000 rpm Atomized cleaning capabilities
Water Handling System	Slot-to-slot integrity Inspection drawer
Standard Features	Automatic alignment Cut verify Kerf inspection Y offset correction
User Interface	Two touch screens: 19" monitor as main screen and 17" monitor for the maintenance NGUI (New Graphic User Interface) Multilanguage support Win 11 OS
Options	Barcode reader High Power spindle up to 2.2KW UV station US83 camera with continuos digital magnification from x70 to x290 Dress station Geometric Model Finder (GMF) Dicing Floor Management
Utilities Electrical Air Spindle Coolant (per spindle) Cutting water (per spindle)	200-240 VAC, 50/60 Hz, single phase 500 L/min 5.5 bar 1.1 L/min Up to 3 L/min
Dimensions WxDxH	1145 mm x 1687 mm x 1830 mm
Weight	1500 kg
Environmental Conditions	Room temperature: 20°C to 25°C (°F) Humidity: Less than 70% relative humidity (noncondensing) Cutting water/Spindle water Temperature fluctuation: °F Floor must be vibration-free
Enviromental	Room Temperture: 20°C ± 1°C (77°F ± 1.8°F) Humidity: Less than 70% relative humidity (non-condensing) Cutting water / Spindle Water Temperature ± 1°C (±1.8°F) The floor must be vibration-free

Note: Specifications are subject to change without notice.

